



Material Content Data Sheet



Sales Product Name		TLD1125EL		Issued		28. August 2013		
MA#		MA001137896						
Package		PG-SSOP-14-5		Weight*		82.77 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.376	1.66	1.66	16630	16630
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8325	
wire	non noble metal	copper	7440-50-8	27.978	33.80	34.68	338038	346883
	non noble metal	copper	7440-50-8	0.081	0.10	0.10	976	976
	organic material	carbon black	1333-86-4	0.101	0.12		1217	
encapsulation	plastics	epoxy resin	-	4.634	5.60		55991	
	inorganic material	silicondioxide	60676-86-0	45.636	55.14	60.86	551391	608599
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11794	11794
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9275	9275
glue	plastics	epoxy resin	-	0.121	0.15		1461	
	noble metal	silver	7440-22-4	0.363	0.44	0.59	4382	5843
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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